HOSTAFORM® C 9021 LS 10/1570

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Chemical abbreviation according to ISO 1043-1: POM Molding compound ISO 29988- POM-K, M-GCL, 03-002 POM copolymer Injection molding type, UV-stabilized with UV-stabilizers and carbon black; good chemical resistance to solvents, fuel and strong alkalis as well as good hydrolysis resistance; high resistance to thermal and oxidative degradation. Burning rate ISO 3795 and FMVSS 302 < 100 mm/min for a thickness more than 1 mm. Ranges of applications: exterior applications. FMVSS = Federal Motor Vehicle Safety Standard (USA)

Product information

Resin Identification	POM		ISO 1043
Part Marking Code	>POM<		ISO 11469

Rheological properties

Melt volume-flow rate	8	cm^3/10min	ISO 1133
Temperature	374	°F	
Load	4.76	lb	
Molding shrinkage, parallel	2.0	%	ISO 294-4, 2577
Molding shrinkage, normal	1.8	%	ISO 294-4, 2577

Typical mechanical properties

Tensile modulus	413000	psi	ISO 527-1/-2
Tensile stress at yield, 50mm/min	9300	psi	ISO 527-1/-2
Tensile strain at yield, 50mm/min	8	%	ISO 527-1/-2
Nominal strain at break	25	%	ISO 527-1/-2
Tensile creep modulus, 1h	363000	psi	ISO 899-1
Tensile creep modulus, 1000h	203000	psi	ISO 899-1
Charpy impact strength, 23°C	52.3	$ftlb/in^2$	ISO 179/1eU
Charpy impact strength, -30°C	52.3	$ftlb/in^2$	ISO 179/1eU
Charpy notched impact strength, 23°C	3.09	$ftlb/in^2$	ISO 179/1eA
Charpy notched impact strength, -30°C	2.85	$ftlb/in^2$	ISO 179/1eA

Thermal properties

Melting temperature, 10°C/min	333	°F	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	221	°F	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	0.61	E-4/°F	ISO 11359-1/-2

Electrical properties

Volume resistivity	1E12	Ohm.m	IEC 62631-3-1
Surface resistivity	1E14	Ohm	IEC 62631-3-2
Electric strength	711	kV/in	IEC 60243-1
Comparative tracking index	300		IEC 60112

Physical/Other properties

Humidity absorption, 2mm	0.2	%	Sim. to ISO 62
Water absorption, 2mm	0.65	%	Sim. to ISO 62
Density	0.0513	lb/in^3	ISO 1183

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Injection

Drying Recommended	no	
Drying Temperature	212	°F
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	392	°F
Min. melt temperature	374	°F
Max. melt temperature	410	°F
Max. screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	212	°F
Min. mold temperature	176	°F
Max. mold temperature	248	°F
Hold pressure range	8700 - 17400	psi
Hold Pressure Time (h is the max. wall thickness of the part in mm)	$2h^2$-3	s

Characteristics

Processing	Injection Molding
Additives	Release agent
Special characteristics	Light stabilized or stable to light, U.V. stabilized or stable to weather

Additional information

Injection molding

Preprocessing

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

Processing

Standard injection moulding machines with three phase (15 to 25 D) plasticating screws will fit.

Postprocessing

Conditioning e.g. moisturizing is not necessary.

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